RD-ECR (Engineering Change Request)

申請人: 硬體課/譚德和 Kevin_Tan　　表單號: 105　申請日期: 2026-09-08

Proposed Change	☐ Design modification 設計修改 ☑ Second source change 替代料變更 ☐ Material change 材料變更 ☐ Manufacturer change 製造商變更 ☐ Process sequency change 工序變更 ☐ Factory change 工廠變更 ☐ Equipment/Tooling change 設備/模具變更 ☐ Process/Method/Condition change 加工流程/方法 /條件變更 ☐ Others 其他			EC No	EC26090401
-	N/A			Initiator	譚德和 Kevin_Tan(D0705)
Reason for Change	Due to the 3CC47616MLW shortage issue, add second source 3CC47616MLT.			Issue Date	2026-09-08
Model / Part No	Please refer to the attached file.			Requester Dept	DV11M016-採購課
Implementation Type	○ 1. Immediately Change 立即切換 ◉ 2. Running Change 自然切換 ○ 3. Other 其他			-	N/A
PM	王志維 Ryan_Wang(D0480)	Sales	陳冠華 Oliver_Chen(D0525)	File attached 附件上傳	3CC47616MLW_ MLCC Co... Product Validation Report... 設計變更審查會議記錄-G版... 備忘錄樣式.pdf 影響機種.pdf
Customer Approval	○ Needed ◉ Not needed	Customer Name	N/A	Customer Sign-off Area 客戶簽核	
Invalid	◉ No ○ Yes	-	N/A		

Material Change Description 物料變更說明

No	Subassembly	T	PartNo	Description	Qty	Location	Stock	Remark
1	2AAD186R03C	B						
1	2AAD186R03C	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	12.000	C53,C59,C64,C69,C75,C80,C150,C163,C166,C167,C178,C179		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
2	2AAD279R03G	B						
2	2AAD279R03G	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	1.000	C8		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
3	2AAD536R038	B						
3	2AAD536R038	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	15.000	C111,C119,C121,C125,C127,C132,C135,C138,C150,C155,C166,C210,C211,C215,C705		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
4	2AAD536R138	B						
4	2AAD536R138	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	15.000	C111,C119,C121,C125,C127,C132,C135,C138,C150,C155,C166,C210,C211,C215,C705		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
5	2AAD539014S	B						
5	2AAD539014S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	2.000	C128,C131		1st : 3CC47616MLT 2nd: 3CC47616MLW
6	2AAD539R038	B						
6	2AAD539R038	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	3.000	C128,C131,C134		1st : 3CC47616MLT 2nd: 3CC47616MLW
7	2AAD539R138	B						
7	2AAD539R138	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	3.000	C128,C131,C134		1st : 3CC47616MLT 2nd: 3CC47616MLW
8	2AAD587R038	B						
8	2AAD587R038	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	7.000	C6,C33,C38,C56,C63,C70,C112		1st : 3CC47616MLT 2nd: 3CC47616MLW
9	2AAD606R038	B						
9	2AAD606R038	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	10.000	C112,C115,C118,C120,C123,C126,C130,C915,C931,C960		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
10	2AAD613054S	B						
10	2AAD613054S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	18.000	C1022,C1023,C108,C114,C141,C144,C156,C157,C160,C161,C502,C503,C509,C511,C713,C714,C873,C874		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
11	2AAD619014S	B						
11	2AAD619014S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	22.000	C117,C118,C1405,C1410,C171,C172,C176,C179,C181,C185,C187,C190,C210,C213,C216,C219,C221,C225,C575,C578,C595,C598		1st : 3CC47616MLT 2nd: 3CC47616MLW 刪除 3CC47625MLM
12	2AAD674014S	B						
12	2AAD674014S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	5.000	C606,C618,C621,C624,C625		1st : 3CC47616MLT 2nd: 3CC47616MLW
13	2AAD695014S	B						

No	Subassembly	T	PartNo	Description	Qty	Location	Stock	Remark
13	2AAD695014S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	4.000	C1153,C1154,C1167,C1168		1st : 3CC47616MLT 2nd: 3CC47616MLW
14	2AAD697014S	B						
14	2AAD697014S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	3.000	C128,C131,C134		1st : 3CC47616MLT 2nd: 3CC47616MLW
15	2AAD698014S	B						
15	2AAD698014S	A	3CC47616MLT	CC (47U,16V,X5R,M,1206,TAIYO)	2.000	C128,C131		1st : 3CC47616MLT 2nd: 3CC47616MLW

Engineering Change Assessment Item List 工程變更評估項目清單

1. Application for Revision of Specification or Drawing(s) for delivery 是否有修改交貨的規格或圖面	1.Confirm	○ Yes ● No need	1.Remark	N/A
2. Standards or Regulatories impact 是否有評估適用之標準或主管機關之相關法規的申請	2.Confirm	○ Yes ● No need	2.Remark	無影響
3. Change point of PCB mounting PCBA插件位置是否變更	3.Confirm	○ Yes ● No need	3.Remark	N/A
4. PCBA Process Changes PCBA製程是否變更	4.Confirm	○ Yes (Continue checking below) ● No	4.Remark	N/A
_ 4-1) Change of Reflow temperature 迴焊溫度是否變更	4-1 Confirm	○ Yes ● No need	4-1.Remark	N/A
_ 4-2) Change of bonding temperature 膠合溫度是否變更	4-2 Confirm	○ Yes ● No need	4-2.Remark	N/A
_ 4-3) Change of Manual Soldering temperature 人工手焊工具之溫度是否變更	4-3 Confirm	○ Yes ● No need	4-3.Remark	N/A
_ 4-4) Change of storage condition after protection humidity package 防潮包裝完成後的儲存條件是否變更	4-4 Confirm	○ Yes ● No need	4-4.Remark	N/A
5. Reliability test report(Test result and data) 是否有可靠性測試報告(測試結果及數據)	5.Confirm	● Yes ○ No need	5.Remark	參考附件
6. Process FMEA(Medical only) 是否有進行製程失效模式與效應分析	6.Confirm	○ Yes ● No need	6.Remark	N/A
7. Design FMEA(Medical only) 是否有進行設計失效模式與交應分析	7.Confirm	○ Yes ● No need	7.Remark	N/A
8. Risk Management(Medical only) 是否有進行風險管理評估	8.Confirm	○ Yes ● No need	8.Remark	N/A
9. Change points due to the modification 是否此修改會延伸導致其他變更點	9.Confirm	○ Yes ● No need	9.Remark	N/A
10. Initial Supply Control implements plan or result 是否有實施供料控制評估	10.Confirm	○ Yes ● No need	10.Remark	替代料Running change
_ 10-1) Confirm the work order or order number or date for the implementation start of the engineering change 確認工程變更開始實施之工單或訂單號碼或日期	10-1 Confirm	○ Yes ● No need	10-1.Remark	工單缺料切換替代料
_ 10-2) Coordinate the handling methods for related products and materials 協調相關產品及材料處理方法	10-2 Confirm	○ Yes ● No need	10-2.Remark	替代料Running change
_ 10-3) Arrange th production schedule 處理生產日程之安排	10-3 Confirm	○ Yes ● No need	10-3.Remark	替代料Running change

_ 10-4) Control the changed materials 變更材料之管制	10-4 Confrim	○ Yes ◉ No need	10-4.Remark	無需變更材料管制
_ 10-5) Establish relevant execution control records for EC materials, register traceability data for each material 建立有關工程變更物料之相關執行管控記錄、登錄各項物料追溯性資料	10-5 Confirm	○ Yes ◉ No need	10-5.Remark	替代料Running change
11. Training Requirement 若此一變更影響製程或檢驗，是否需要再做人員訓練	11.Confrim	○ Yes ◉ No need	11.Remark	N/A
12-1. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-1 Confirm	☐ QC control plan ☐ Service Manual ☐ Others ☑ Not needed	12-1.Remark	NA
12-2. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-2 Confirm	☐ SIP ☐ SOP ☐ Others ☑ No need	12-2.Remark	No need.
12-3. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下)	12-3 Confirm	☑ MDF ☑ DMR ☐ Approval Sheet ☐ Engineering Spec ☐ Others ☑ Not needed	12-3.Remark	N/A
DIVA 鈺緯科技開發股份有限公司		版本：C		表單編號：QR-736-05

簽核列表 ◉ 表格 ○ 圖形

序號	簽核人	簽核結果	簽核意見
1	**盧俊宇 Jackylu** 二階主管(課/部級)	**否決** 2026-09-09 08:47	描述請再次確認.. 應該都是1206 . 不會有1207~1221 這種描述
2	**譚德和 Kevin_Tan** 重新送簽	**重新送簽** 2026-09-09 08:55	
3	**盧俊宇 Jackylu** 二階主管(課/部級)	**同意** 2026-09-09 09:50	
4	**林雪清 Joe_Lin** ECR-DQE人員	**同意** 2026-09-09 09:57	測試報告如附件
4	**林金封 Jim_Lin** ECR-DQE人員	**同意** 2026-09-09 10:10	N/A
4	**張鈞凱 Ericchang** ECR-DQE人員	**同意** 2026-09-09 10:37	無影響EMI
4	**呂旻峰 Jack** ECR-DQE人員	**同意** 2026-09-09 14:54	N/A
5	**廖榮棋 Rongchi_Liao** DQE主管	**同意** 2026-09-10 08:51	
6	**劉証瑋 Dennis_Liu** [陳冠華 Oliver_Chen 加簽]Sales	**同意** 2026-09-10 13:27	
7	**胡靜文 Estela_Hu** [陳冠華 Oliver_Chen 加簽]Sales	**同意** 2026-09-10 13:34	
8	**陳冠華 Oliver_Chen** Sales	**同意** 2026-09-10 13:49	
8	**王志維 Ryan_Wang** PM	**同意** 2026-09-11 09:18	
9	**楊建勛 Michael_Young** R&D Director [通知]	**同意** 2026-09-11 09:18	[通知]
10	**蕭玉桃 Momohsiao** ECR-PIC人員	**同意** 2026-09-11 09:23	
11	**王世炫 Hsuan_Wang** ECR-PE人員	**同意** 2026-09-11 09:57	
12	**林益銓 Nick_Lin** PE	**同意** 2026-09-11 23:51	

序號	簽核人	簽核結果	簽核意見
13	**黃振哲 Terry_Huang** ECR-PMC人員	**同意** 2026-09-14 09:32	
14	**邱羽萱 Lily_Chiu** PMC	**同意** 2026-09-14 09:40	
15	**李慧珊 Sandra** ECR-SCM人員	**同意** 2026-09-14 09:46	
15	**郭修榮 Omega_Kuo** PD	**同意** 2026-09-14 10:04	
15	**黃瓊玉 Joannehuang** ECR-PD人員	**同意** 2026-09-14 10:45	
16	**李妍樂 Alina_Lee** [李慧珊 Sandra 加簽]	**同意** 2026-09-14 17:19	
17	**李金龍 Kevin_Lee** ECR-QA人員	**同意** 2026-09-15 09:17	
18	**陳泰盛 Tyson_Chen** QA	**同意** 2026-09-15 09:32	
19	**楊建勛 Michael_Young** R&D Director	**同意** 2026-09-15 09:54	
20	**蕭玉桃 Momohsiao** ECR-PIC人員	**同意** 2026-09-16 11:32	
21	**譚德和 Kevin_Tan** SAP核發	**同意** 2026-09-16 14:35	